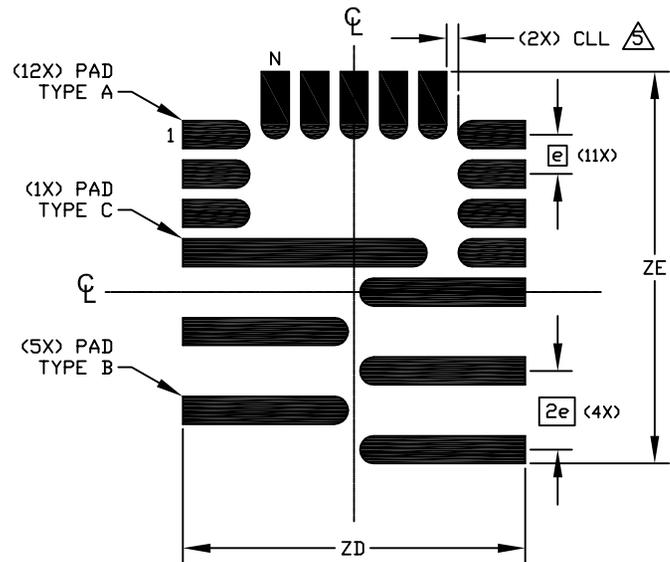
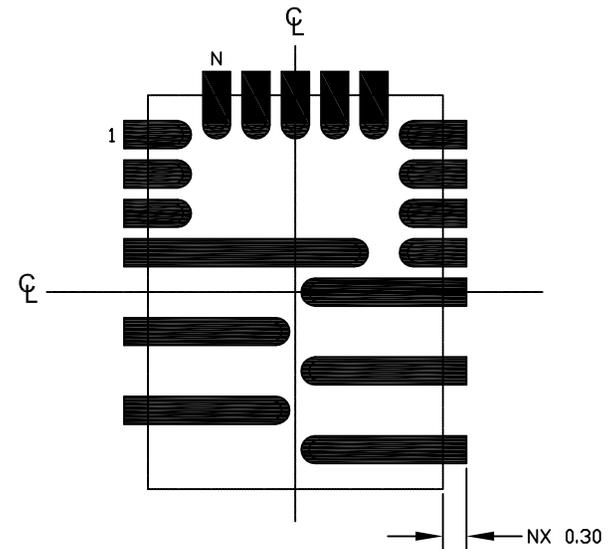


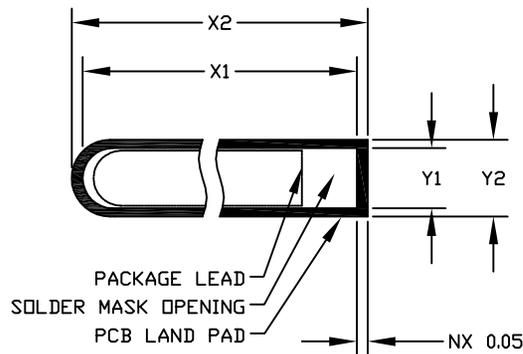
### RECOMMENDED LAND PATTERN



### PACKAGE OVERLAY



### PAD DETAIL INFORMATION



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
CLL	0.15	REF		.006	REF	
e	0.50	BSC		.020	BSC	
N	18	PINS		18	PINS	
ZD	4.35	REF		.171	REF	
ZE	4.98	REF		.196	REF	

DIM	MILLIMETERS			INCHES		
	TYPE A	TYPE B	TYPE C	TYPE A	TYPE B	TYPE C
Y1	0.28	0.28	0.28	.011	.011	.011
Y2	0.35	0.35	0.35	.014	.014	.014
X1	0.75	2.00	3.00	.030	.079	.118
X2	0.85	2.10	3.10	.033	.083	.122

#### NOTES:

1. REFERENCE PKG. OUTLINE: 21-0997
  2. LAND PATTERN COMPLIES TO: IPC7351A.
  3. ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODE ONLY.
  4. ALL DIMENSIONS IN MM.
- △ CLL IS THE CORNER PAD EDGE TO ADJACENT INSIDE PAD DISTANCE.

—DRAWING NOT TO SCALE—



TITLE:  
PACKAGE LAND PATTERN,  
[P183A5F+1] FCQFN

APPROVAL

DOCUMENT CONTROL NO.

REV.

1/1

90-0501

A

1/1

This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use.

This document is subject to change without notice.

Contact technical support at <http://www.maximintegrated.com/support> for further questions.